



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: The Application of

Katherine G. Heinen, et al.

Serial No.: 09/186,973

Filed: 11/05/98

For: Wafer-Scale Assembly of Chip-Size Packages

Docket Number: TI-23158

Art Unit: 2823

Examiner: R. Shukla

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REQUEST TO CORRECT FILING RECEIPT

Assistant Commissioner
for Patents
Washington, DC 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is being deposited with
the U.S. Postal Service on 8-29-01 as First
Class Mail in an envelope addressed to: Assistant Commissioner for
Patents, Washington, D.C.

Karen Vertz 8-29-01
Karen Vertz Date

Enclosed is a photocopy of the Filing Receipt (PTO-103X) received from the United States Patent and Trademark Office in the above-identified application. The filing receipt is erroneous since it does not show priority under 35 U.S.C. § 119(e)(1) of provisional application number 60/066,256 filed 11/20/97. Priority was requested as reflected on the enclosed transmittal form mailed in with the non-provisional application. To the extent that it is considered necessary for such demand to be made at the current time, demand for priority under 35 U.S.C. § 119(e)(1) of provisional application number 60/066,256 filed 11/20/97 is hereby made.

Please also amend the spelling of the circled word to **ASSEMBLY**.

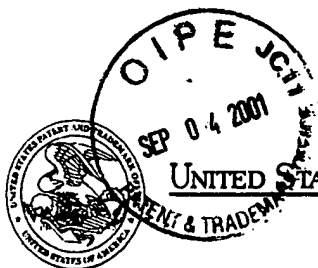
Applicants respectfully request a corrected Filing Receipt (Form PTO-103X) and believe that Applicants did not cause this error and that no fee is due. However, this letter authorizes any necessary charges to Deposit Account No. 20-0668 of Texas Instruments Incorporated.

Respectfully submitted,

Gary C. Honeycutt
Gary C. Honeycutt
Registration No. 20,250
Attorney for Applicants

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265
(972) 238-7160
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GCH



UNITED STATES PATENT AND TRADEMARK OFFICE

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UNITED STATES PATENT AND TRADEMARK OFFICE
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/186,973	11/05/1998	2823	872	1000-2035	6	18	4

T123158

CONFIRMATION NO. 2495

23494
TEXAS INSTRUMENTS INCORPORATED
P O BOX 655474, M/S 3999
DALLAS, TX 75265

CORRECTED FILING RECEIPT



OC000000006440120

Date Mailed: 08/17/2001

Receipt is acknowledged of a CPA in this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

KATHERINE G. HEINEN, DALLAS, TX;
DARVIN R. EDWARDS, GARLAND, TX;
ELIZABETH G. JACOBS, RICHARDSON, TX;

Domestic Priority data as claimed by applicant

Provisional Application No. 60/066,256 11/20/97

Foreign Applications

If Required, Foreign Filing License Granted 08/16/2001

CPA filed on: 05/17/2001

Projected Publication Date: 11/22/2001

Non-Publication Request: No

Early Publication Request: No

Title

WAFER-SCALE ASSEMBLY OF CHIP-SIZE PACKAGES

ASSEMBLY

Preliminary Class

438

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NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b)
TRANSMITTAL FORM

Attorney Docket No. TI-26059

Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the
patent application of:

Inventor(s): Katherine G. Heinen
Darvin R. Edwards
Elizabeth G. Jacobs

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"EXPRESS MAILING" Mailing Label No.
EE528827016US. Date of Deposit: November 5, 1998.
I hereby certify that this paper is being deposited with the
U.S. Postal Service Express Mail Post Office to Addressee
Service under 37 CFR 1.10 on the date shown above and is
addressed to the Assistant Commissioner for Patents,
Washington, D.C. 20231.

Lynna Van Deventer
Lynna Van Deventer

For: Wafer-Scale Assembly of Chip-Size Packages

Enclosed are:

- 6 sheets of informal drawings and 20 pages of Specification (including Abstract)
x A Declaration/Power of Attorney
x Assignment with form PTO 1595

Please amend the specification by inserting before the first line the sentence:

This application claims priority under 35 USC § 119 (e) (1) of provisional application number 60/066,256,
filed 11/20/97.

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 790.00
Total Claims	18	-20 =	0	X \$22 =	\$0.00
Independent Claims	4	- 3 =	1	X \$82 =	\$82.00
Total Filing Fee					\$872.00

Please charge Deposit Account No. 20-0688 in the amount of the Total Fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0688. This form is submitted in triplicate.

All correspondence related to this application may be addressed to the undersigned at Klinger & Navarro, L.L.P. 801 E. Campbell Rd. Suite 655, RICHARDSON, TX 75081.

Date: November 5, 1998

Gary C. Honeycutt
Gary C. Honeycutt
Registration No. 20,250